

Title (en)

PLANARIZATION FOR SEMICONDUCTOR DEVICE PACKAGE FABRICATION PROCESSES

Title (de)

PLANARISIERUNG FÜR VERFAHREN ZUR HERSTELLUNG VON HALBLEITERBAUELEMENTGEHÄUSEN

Title (fr)

PLANARISATION POUR PROCESSUS DE FABRICATION DE BOÎTIER DE DISPOSITIF À SEMI-CONDUCTEUR

Publication

EP 3766097 A4 20220413 (EN)

Application

EP 19766870 A 20190215

Priority

- US 201862643222 P 20180315
- US 2019018154 W 20190215

Abstract (en)

[origin: WO2019177742A1] A method of electronic device package fabrication includes dispensing a planarizing liquid into a region between adjacent features that protrude from a substrate. The planarizing liquid is then processed to provide a hardened, substantially solid material in the region between adjacent features. In some examples, the planarizing liquid can be a dielectric material used in the formation of multilevel redistribution layers or a packaging resin material used for packaging semiconductor chips. A planarization apparatus of an example includes a substrate support, a liquid dispensing system configured to dispense the planarizing liquid onto the substrate, a hardening system for hardening the planarizing liquid, and a planar element system to press into the planarizing liquid.

IPC 8 full level

H01L 21/56 (2006.01); **H01L 23/31** (2006.01)

CPC (source: EP KR)

H01L 21/56 (2013.01 - EP KR); **H01L 21/561** (2013.01 - EP); **H01L 21/565** (2013.01 - EP); **H01L 23/293** (2013.01 - KR); **H01L 23/31** (2013.01 - KR); **H01L 23/3114** (2013.01 - EP)

Citation (search report)

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Designated contracting state (EPC)

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DOCDB simple family (publication)

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DOCDB simple family (application)

US 2019018154 W 20190215; CN 201980019163 A 20190215; EP 19766870 A 20190215; JP 2020547376 A 20190215; KR 20207029381 A 20190215; TW 108105230 A 20190218